

MEMS PACKAGING USING A NON-SILICON SUBSTRATE FOR  
ENCAPSULATION AND INTERCONNECTION

Abstract

A MEMS die is bonded to a cap to form a MEMS device.

- 5 The cap is non-silicon and has an electrical via extending from one side of the cap to another side of the cap. In one embodiment, a plurality of caps is wafer bonded to a plurality of MEMS dice.